

## REMARKS

### Summary

In the Office Action, claims 1-19 stand rejected. Claims 1-19 are rejected under 35 U.S.C. § 112, second paragraph, as well as under § 102 as being anticipated by U.S. Patent No. 6,975,063 issued to Mao et al. ("Mao").

In response, claims 1, 2, 4, 5, 8, 10, 15, and 17 have been amended, and claims 12-14 and 16 have been cancelled. In addition, new claims 31-36 have been added. No new has been introduced.

### Rejections under 35 U.S.C. § 112, second paragraph

Claims 1-19 are rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for allegedly failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention. Specifically, it is alleged that in claim 1, the "metal solution" is not clear. Although Applicant respectfully asserts that the invention as claimed read in light of the specification is in fact definite and distinctly claims the subject matter which the Applicant regards as the invention, Applicant nonetheless has amended independent claim 1 in the interest of expediting prosecution of this application. All amendments are fully supported by the original disclosure and no new matter has been added. The amendment places the pending claims in condition of allowance.

### Rejections under 35 U.S.C. § 102

Claims 1-19 stand rejected under 35 U.S.C. § 102 as being anticipated by Mao. Claims 12-14 and 16 have been cancelled thereby rendering moot the rejections thereof. In addition, claim 1 has been amended to clarify the scope of the claim, placing said claim and claims 2-11, 15, and 17-19 depending therefrom, either directly or via an intervening claim, in condition for allowance.

Claim 1, as amended, is directed to a method for forming an integrated circuit comprising forming or providing a solution containing metal ions and carbon nanotubes; and co-depositing the metal ions and the carbon nanotubes onto a substrate utilizing the solution, said co-depositing including a selected one of co-electroplating, co-electroless plating, co-electrophoretically deposition, and spin-coating.

Mao fails to teach the invention of claim 1. Rather, Mao discloses a method for making metallized carbon nanotubes using an electroless plating technique, i.e., plating metal directly onto carbon nanotubes. Mao, Abstract; 4:20-26. That is, rather than co-depositing metal ions and carbon nanotubes onto a substrate, Mao teaches electroplating metal onto carbon nanotubes. Thus, Mao cannot be said to anticipate the claim 1.

Furthermore, even if one were to consider deposition of Mao's metallized carbon nanotubes to be "co-depositing," one could not also say that Mao's deposition is co-deposition of metal ions and carbon nanotubes. Rather, Mao's metallized carbon nanotubes are removed from the reaction solution (i.e., the solution in which the metal is electroplated onto carbon nanotubes) and then dispersed into a solvent, the solvent then may be applied to a substrate. Mao, 4:25-26; 6:1-12. Thus, the metal of Mao's metallized carbon nanotubes is no longer ionic at the point in which they are deposited onto a substrate. Thus, for at least this further reason, Mao cannot be said to anticipate the claim 1.

Accordingly, claim 1 is allowable over Mao. Claims 2-11, 15, and 17-19 depend from claim 1, either directly or via an intervening claim, and are therefore also allowable for at least the same reasons.

## CONCLUSION

In view of the foregoing, Applicant respectfully submits that all pending claims are in condition of allowance. Thus, entry of the offered amendments and early issuance of Notice of Allowance is respectfully requested.

The Commissioner is hereby authorized to charge shortages or credit overpayments to Deposit Account No. 500393.

Respectfully submitted,  
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